

# Table of Contents

<b>Grain Boundary Diffusion and Oxidation Processes</b>	
J. Philibert	1
<b>Influence of Grain Boundary Diffusion on Thin Film Reactions</b>	
P. Gas	9
<b>Motion of the Grain Boundary System with the Triple Junctions</b>	
L.S. Shvindlerman, G. Gottstein, U. Czubayko and V.G. Sursaeva	11
<b>Study of Grain-Boundary Diffusion of Au in Copper within <math>\Sigma 5</math> Misorientation Range in the Context of Structure of Grain Boundaries</b>	
E. Budke, C. Herzig, S.I. Prokofjev and L.S. Shvindlerman	21
<b>Grain Boundary Diffusion in Polycrystalline Solids with an Arbitrary Grain Size</b>	
S.V. Divinski	35
<b>Pseudo Type-B Diffusion Regime in Cu Grain Boundaries below 250°C</b>	
D. Gupta	43
<b>Segregation and Grain Boundary Diffusion in Metals and Elemental Semi-Conductors</b>	
J. Bernardini	49
<b>Nonlinear Segregation Effects on Grain Boundary Heterodiffusion Extraction of Segregation Term from a Triple Product</b>	
B.S. Bokstein and A. Ostrovsky	51
<b>Solute Diffusion and Segregation in Grain Boundaries of Silver and Copper</b>	
T. Surholt, C. Minkwitz and C. Herzig	59
<b>Grain Boundary Diffusion and Stability of the Triple Junctions</b>	
A.N. Aleshin, W. Gust, E. Rabkin and L.S. Shvindlerman	75
<b>A New Method for Grain Boundary Diffusion Coefficient Measurement</b>	
R. Le Gall, G. Saindrenan and D. Roptin	85
<b>Complex Atomic-Scale Dynamics in Grain Boundaries in Silicon</b>	
S.T. Pantelides, A. Maiti, M.F. Chisholm and S.J. Pennycook	95
<b>Relation Between Segregation at Interfaces, Structure and Diffusion in Germanium</b>	
A. Charai, A. Rolland and F. Cabané	97
<b>Microscopic Investigation of Surface Segregation in Random Alloys</b>	
A.Y. Lozovoi, P.A. Korzhavyi and Y.K. Vekilov	107
<b>Segregation, Phase Separation and Grain Boundary Diffusion in Thin Films</b>	
C. Cserháti, D.L. Beke and I.A. Szabó	121
<b>AES Study of the Mass Transport of Nickel Near Ni / Cu (111) Interface</b>	
Z. Tókei, D.L. Beke, J. Bernardini and A. Rolland	129
<b>Grain Boundary Segregation in the Cu-Bi System</b>	
L.S. Chang, E. Rabkin, B.B. Straumal, S. Hofmann, B. Baretzky and W. Gust	135
<b>Grain Boundary Electromigration in Thin Films: Interface Reaction and Segregation Effects</b>	
E.E. Glickman	147
<b>Grain Boundary Diffusion, Electromigration and Segregation in Cu and Cu-2wt% Sn Alloy</b>	
D. Gupta	161
<b>The Effect of Pressure on Grain Boundary Wetting, Segregation and Diffusion</b>	
W. Łojkowski, E. Rabkin, B.B. Straumal, L.S. Shvindlerman and W. Gust	163
<b>Strain Induced Grain Boundary Premelting due to Heavy Pile-Up of Screw Dislocations in Deformed Copper Bicrystals</b>	
F. Inoko, T. Okada and T. Yoshikawa	175
<b>Copper Diffusion in Nickel Thin Film under Stresses in the Kinetic Regime 'B'</b>	
N. Balandina, B.S. Bokstein and A. Ostrovsky	181
<b>Influence of Precipitates on the Grain Boundary Diffusion: A Perturbative Approach</b>	
N.S. Khader, D.E. Mekki and R.J. Tarento	191
<b>The Manifestations of the Diffusion-Coefficient Distribution Functions of the Grain Boundaries in W and Au Polycrystals</b>	
M.I. Kurkin, S.M. Klotsman, A.N. Timofeyev and V.V. Dyakin	199

<b>The Study of the Diffusion of <math>^{57}\text{Co}</math> in Polycrystalline Gold at the Upper Boundary of Temperature Interval Ordinarily Used in Intercrystallite Diffusion Investigations</b>	205
N.I. Timofeev, S.M. Klotsman, M.I. Kurkin, V.V. Dyakin and V.K. Rudenko	
<b>Low-Temperature Interdiffusion in Binary and Multilayer Thin Film System</b>	215
S.I. Sidorenko, S.M. Voloshko and M.A. Vasiliev	
<b>Exact Solution of Triple Junction Diffusion Problem</b>	223
V.A. Ivanov, A.S. Ostrovsky, A. Petelin and S. Peteline	
<b>Relaxation Processes in Ultrafine-Grained Copper Processed by Severe Plastic Deformation</b>	229
N.M. Amirkhanov and R.K. Islamgaliev	
<b>Growth and Healing of Voids at Grain Boundary during High Temperature Creep</b>	235
V.S. Gostomelskii	
<b>Mechanisms of Grain Boundary Diffusion in Intermetallic Compounds</b>	243
S.V. Divinski and L.N. Larikov	
<b>Grain Boundary Diffusion in Thin Films under Stress Field in Kinetic Regime 'C'</b>	249
A. Ostrovsky	
<b>Round Table Discussion I: Diffusion in Intermetallics</b>	255
<b>Round Table Discussion II: Grain Boundary Wetting and Liquid Grooving</b>	265